

## Product and technology information

- One Stop Packaging Service  
TEG Chip, WLCSP, SIP, W/B, F/C, TSV, 3D Stacked PKG
- Standard TSV TEG wafer sales
- Original TSV-type image sensor
- Licensing of TSV core and technical know-how

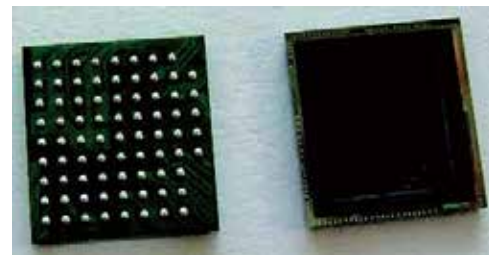
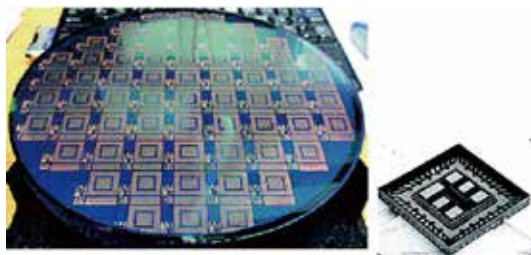
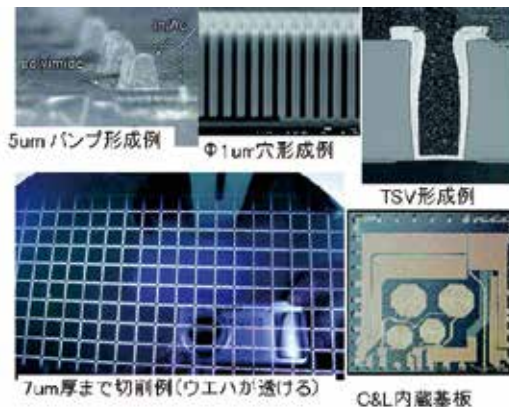
## Company Introduction

ZyCube technology consists of two technologies primarily. One is a 3D LSI wafer multilayer integrated technology that is Professor Mitumasa Koyanagi's research results at Tohoku University Graduate School. Another one is the "high density electronic system integration" research achievements by Manabu Bonkohara at Science Technology Research Association ASET. And combining the two technologies, highly integrated, high-performance electronic systems at low prices are realized.

## Others (Comments)

[Company strength]

Based on the request for development of customer, considering the design, process, materials, and equipment, ZyCube provides optimal prototyping service.



## Company Information

**Corporate name** ZyCube Co., Ltd.

**Representative** Chairman and CEO Manabu Bonkohara

**Capital** 34,000,000 JPY

**Number of Employees** 6

**Person In Charge** Executive Managing Director Akira Nagami

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**Established date** 29.3.2002

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